

Integrated circuits - EMC evaluation of transceivers -  
Part 5: Ethernet transceivers

## EESTI STANDARDI EESSÕNA

## NATIONAL FOREWORD

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Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas.	This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation and Accreditation.
Euroopa standardimisorganisatsioonid on teinud Euroopa standardi rahvuslikele liikmetele kättesaadavaks 04.06.2021.	Date of Availability of the European standard is 04.06.2021.
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ICS 31.200

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English Version

**Integrated circuits - EMC evaluation of transceivers - Part 5:  
Ethernet transceivers  
(IEC 62228-5:2021)**

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récepteurs - Partie 5 : Émetteurs-récepteurs  
(IEC 62228-5:2021)

Integrierte Schaltungen - Bewertung der  
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Empfangsgeräten - Teil 5: Ethernet-Sende-Empfangsgerät  
(IEC 62228-5:2021)

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## European foreword

The text of document 47A/1115/FDIS, future edition 1 of IEC 62228-5, prepared by SC 47A "Integrated circuits" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62228-5:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022-02-28
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2024-05-31

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The text of the International Standard IEC 62228-5:2021 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

CISPR 16-1-1	NOTE	Harmonized as EN IEC 55016-1-1
IEC 61000-4-2	NOTE	Harmonized as EN 61000-4-2
IEC 61000-4-4	NOTE	Harmonized as EN 61000-4-4
IEC 61000-4-5	NOTE	Harmonized as EN 61000-4-5
IEC 61967-2	NOTE	Harmonized as EN 61967-2
IEC 61967-8	NOTE	Harmonized as EN 61967-8
IEC 62132-2	NOTE	Harmonized as EN 62132-2
IEC 62132-8	NOTE	Harmonized as EN 62132-8

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61967-1	-	Integrated circuits - Measurement of electromagnetic emissions - Part 1: General conditions and definitions	EN IEC 61967-1	-
IEC 61967-4	-	Integrated circuits - Measurement of electromagnetic emissions - Part 4: Measurement of conducted emissions - 1 ohm/150 ohm direct coupling method	EN IEC 61967-4	-
IEC 62132-1	-	Integrated circuits - Measurement of electromagnetic immunity - Part 1: General conditions and definitions	EN 62132-1	-
IEC 62132-4	-	Integrated circuits - Measurement of electromagnetic immunity 150 kHz to 1 GHz - Part 4: Direct RF power injection method	EN 62132-4	-
IEC 62215-3	-	Integrated circuits - Measurement of impulse immunity - Part 3: Non-synchronous transient injection method	EN 62215-3	-
IEC 62228-1	-	Integrated circuits – EMC evaluation of transceivers – Part 1: General conditions and definitions	EN IEC 62228-1	-
ISO 10605	-	Road vehicles - Test methods for electrical disturbances from electrostatic discharge	-	-
ISO 21111-2	-	Road vehicles - In-vehicle Ethernet - Part 2: Common physical entity requirements	-	-
ISO 7637-2	-	Road vehicles - Electrical disturbances from conduction and coupling – Part 2: Electrical transient conduction along supply lines only	-	-

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
ISO/IEC/IEEE 8802-3	2017	Information technology - Telecommunications and information exchange between systems - Local and metropolitan area networks - Specific requirements - Part 3: Standard for Ethernet	-	-
+A1	2017		-	-
+A4	2017		-	-
EIA-198-1	-	Electronic Components Industry Association - Ceramic Dielectric Capacitors Classes I, II, III and IV	-	-

# INTERNATIONAL STANDARD



**Integrated circuits – EMC evaluation of transceivers –  
Part 5: Ethernet transceivers**



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# INTERNATIONAL STANDARD



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## Integrated circuits – EMC evaluation of transceivers – Part 5: Ethernet transceivers

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

ICS 31.200

ISBN 978-2-8322-9697-4

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# INTERNATIONAL ELECTROTECHNICAL COMMISSION

## INTEGRATED CIRCUITS – EMC EVALUATION OF TRANSCEIVERS –

### Part 5: Ethernet transceivers

#### FOREWORD

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International Standard IEC 62228-5 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47A/1115/FDIS	47A/1117/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.



This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

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# INTEGRATED CIRCUITS – EMC EVALUATION OF TRANSCEIVERS –

## Part 5: Ethernet transceivers

### 1 Scope

This part of IEC 62228 specifies test and measurement methods for EMC evaluation of Ethernet transceiver ICs under network condition. It defines test configurations, test conditions, test signals, failure criteria, test procedures, test setups and test boards. It is applicable for transceiver of the Ethernet systems

- 100BASE-T1 according to ISO/IEC/IEEE 8802-3/AMD1;
- 100BASE-TX according to ISO/IEC/IEEE 8802-3;
- 1000BASE-T1 according to ISO/IEC/IEEE 8802-3/AMD4

and covers

- the emission of RF disturbances;
- the immunity against RF disturbances;
- the immunity against impulses;
- the immunity against electrostatic discharges (ESD).

### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61967-1, *Integrated circuits – Measurement of electromagnetic emissions – Part 1: General conditions and definitions*

IEC 61967-4, *Integrated circuits – Measurement of electromagnetic emissions, 150 kHz to 1 GHz – Part 4: Measurement of conducted emissions, 1 ohm/150 ohm direct coupling method*

IEC 62132-1, *Integrated circuits – Measurement of electromagnetic immunity – Part 1: General conditions and definitions*

IEC 62132-4, *Integrated circuits – Measurement of electromagnetic immunity 150 kHz to 1 GHz – Part 4: Direct RF power injection method*

IEC 62215-3, *Integrated circuits – Measurement of impulse immunity – Part 3: Non-synchronous transient injection method*

IEC 62228-1, *Integrated circuits – EMC evaluation of transceivers – Part 1: General conditions and definitions*

ISO 10605, *Road vehicles – Test methods for electrical disturbances from electrostatic discharge*

ISO 21111-2, *Road vehicles – In-vehicle Ethernet – Part 2: Common physical entity requirements*

ISO 7637-2, *Road vehicles – Electrical disturbances from conduction and coupling – Part 2: Electrical transient conduction along supply lines only*

ISO/IEC/IEEE 8802-3:2017, *Information technology – Telecommunications and information exchange between systems – Local and metropolitan area networks – Specific requirements – Part 3: Standard for Ethernet*

ISO/IEC/IEEE 8802-3:2017/AMD1:2017, *Amendment 1 – Information technology – Telecommunications and information exchange between systems – Local and metropolitan area networks – Specific requirements – Part 3: Standard for Ethernet – Physical layer specifications and management parameters for 100 Mb/s operation over a single balanced twisted pair cable (100BASE-T1)*

ISO/IEC/IEEE 8802-3:2017/AMD4:2017, *Amendment 4 – Information technology – Telecommunications and information exchange between systems – Local and metropolitan area networks – Specific requirements – Part 3: Standard for Ethernet – Physical layer specifications and management parameters for 1 Gb/s operation over a single twisted-pair copper cable*

Electronic Components Industry Association, EIA-198-1, *Ceramic Dielectric Capacitors Classes I, II, III and IV*

### 3 Terms, definitions and abbreviated terms

For the purposes of this document, the terms and definitions given in IEC 61967-1, IEC 62132-1, IEC 62228-1, as well as the following apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- ISO Online browsing platform: available at <http://www.iso.org/obp>
- IEC Electropedia: available at <http://www.electropedia.org/>

#### 3.1 Terms and definitions

##### 3.1.1

##### **100BASE-T1 transceiver**

transceiver 100 Mbit/s via single balanced twisted pair, with a functionality according to ISO/IEC/IEEE 8802-3/AMD1 (100BASE-T1)

##### 3.1.2

##### **100BASE-TX transceiver**

transceiver 100 Mbit/s via two balanced twisted pairs, with a functionality according to ISO/IEC/IEEE 8802-3(100BASE-TX)

##### 3.1.3

##### **1000BASE-T1 transceiver**

transceiver 1000 Mbit/s via single balanced twisted pair, with a functionality according to ISO/IEC/IEEE 8802-3/AMD4 (1000BASE-T1)

##### 3.1.4

##### **global pin**

pin that carries a signal or power, which enters or leaves the application board without any active component in between